

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Kaoru KATOH</td> <td>10/16/2009</td> </tr> <tr> <td>Shigeki KOYA</td> <td>10/16/2009</td> </tr> <tr> <td>Shinichiro TAKATANI</td> <td>10/16/2009</td> </tr> <tr> <td>Yasushi SHIGENO</td> <td>10/16/2009</td> </tr> <tr> <td>aKISHIGE NAKAJIMA</td> <td>10/16/2009</td> </tr> <tr> <td>Takashi OGAWA</td> <td>10/16/2009</td> </tr> </tbody> </table>		Name	Execution Date	Kaoru KATOH	10/16/2009	Shigeki KOYA	10/16/2009	Shinichiro TAKATANI	10/16/2009	Yasushi SHIGENO	10/16/2009	aKISHIGE NAKAJIMA	10/16/2009	Takashi OGAWA	10/16/2009
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CORRESPONDENCE DATA															
<p>Fax Number: (703)610-8686 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 7036108652 Email: scorey@milesstockbridge.com Correspondent Name: Mitchell W. Shapiro Address Line 1: 1751 Pinnacle Drive, Suite 500 Address Line 4: McLean, VIRGINIA 22102-3833</p>															
ATTORNEY DOCKET NUMBER:	XA-11474/T3662-17515US01														
NAME OF SUBMITTER:	Mitchell W. Shapiro														

CH \$40.00 12615525

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**PATENT
 REEL: 023841 FRAME: 0354**

Total Attachments: 2
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ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by RENESAS TECHNOLOGY CORP., a corporation organized under the laws of Japan, located at 6-2, Otemachi 2-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said RENESAS TECHNOLOGY CORP., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR INTEGRATED CIRCUIT AND HIGH FREQUENCY MODULE WITH THE SAME

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire owner-ship of the said Letters Patent when granted, to be held and enjoyed by said RENESAS TECHNOLOGY CORP., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said RENESAS TECHNOLOGY CORP.,

Signed on the date(s) indicated aside signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Kaoru Katoh</u> (Kaoru KATOH)	<u>10/16/2009</u>
2) <u>Shigeki Koya</u> (Shigeki KOYA)	<u>10/16/2009</u>
3) _____ (Shinichiro TAKATANI)	_____
4) <u>Yasushi Shigeno</u> (Yasushi SHIGENO)	<u>10/16/2009</u>
5) <u>Akishige Nakajima</u> (Akishige NAKAJIMA)	<u>10/16/2009</u>
6) <u>Takashi Ogawa</u> (Takashi OGAWA)	<u>10/16/2009</u>
7) _____	_____

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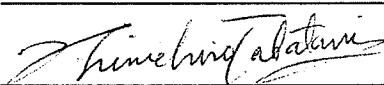
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1) _____ (Kaoru KATOH)	_____
2) _____ (Shigeki KOYA)	_____
3)  _____ (Shinichiro TAKATANI)	10/30/2009
4) _____ (Yasushi SHIGENO)	_____
5) _____ (Akishige NAKAJIMA)	_____
6) _____ (Takashi OGAWA)	_____
7) _____	_____